

RD3G600GN

Nch 40V 60A Power MOSFET

| V _{DSS} | 40V |
|----------------------------|-------|
| R _{DS(on)} (Max.) | 3.6mΩ |
| I _D | ±60A |
| P _D | 40W |

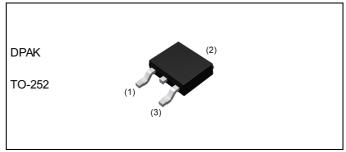
●Features

- 1) Low on resistance
- 2) High power package (TO-252)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen free

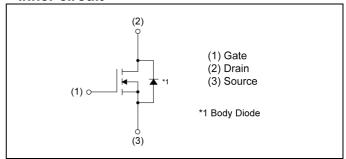
Application

Switching

Outline



●Inner circuit



Packaging specifications

| - r working opcomoducine | | | | | |
|--------------------------|-----------------|------------------|--|--|--|
| | Packing | Embossed Tape | | | |
| | Reel size (mm) | 330 | | | |
| Туре | Tape width (mm) | 16 | | | |
| | Quantity (pcs) | 2500 | | | |
| | Taping code | TL | | | |
| | Marking | RD3G600GN | | | |

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|--------------------|-------------|------|
| Drain - Source voltage | V_{DSS} | 40 | V |
| Continuous drain current | I _D *1 | ±60 | Α |
| Pulsed drain current | I _{DP} *2 | ±120 | Α |
| Gate - Source voltage | V _{GSS} | ±20 | V |
| Avalanche current, single pulse | I _{AS} *3 | 60 | Α |
| Avalanche energy, single pulse | E _{AS} *3 | 70 | mJ |
| Power dissipation | P _D *1 | 40 | W |
| Junction temperature | T _j | 150 | °C |
| Operating junction and storage temperature range | T _{stg} | -55 to +150 | °C |

●Thermal resistance

| Parameter | Symbol | Values | | | Lloit |
|-------------------------------------|----------------------|--------|------|------|-------|
| | | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} *1 | - | 1 | 3.1 | °C/W |

● Electrical characteristics (T_a = 25°C)

| Darameter | Symbol | Conditions | Va | | Values | | |
|--|---|--|------|------|--------|-------|--|
| Parameter | Symbol | | Min. | Тур. | Max. | Unit | |
| Drain - Source breakdown voltage | V _{(BR)DSS} | $V_{GS} = 0V, I_D = 1mA$ | 40 | - | - | V | |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$ | I _D = 1mA referenced to 25°C | - | 26.2 | - | mV/°C | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 40V, V _{GS} = 0V | - | - | 1 | μA | |
| Gate - Source leakage current | I _{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | 1 | 1 | ±500 | nA | |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 1mA$ | 1.0 | - | 2.5 | V | |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_j}$ | I _D = 1mA referenced to 25°C | - | -4.9 | - | mV/°C | |
| Static drain - source | D *4 | V _{GS} = 10V, I _D = 60A | - | 2.8 | 3.6 | mΩ | |
| on - state resistance | R _{DS(on)} *4 | V _{GS} = 4.5V, I _D = 60A | ı | 3.3 | 4.3 | 11122 | |
| Gate resistance | R_G | f = 1MHz, open drain | - | 2.0 | - | Ω | |
| Forward Transfer Admittance | Y _{fs} *4 | V _{DS} = 5V, I _D = 30A | 30 | - | - | S | |

^{*1} T_c=25°C, Limited only by maximum temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \simeq 0.02mH, V_{DD} = 32V, R_G = 25 Ω , Starting T_i = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C)

| Daramatar | Cymahal | Conditions | Values | | | Lleit | |
|------------------------------|------------------------|-----------------------------------|--------|------|------|-------|--|
| Parameter | Symbol Conditions | | Min. | Тур. | Max. | Unit | |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 3400 | - | | |
| Output capacitance | C _{oss} | V _{DS} = 20V | - | 550 | - | pF | |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | - | 150 | - | | |
| Turn - on delay time | t _{d(on)} *4 | $V_{DD} \simeq 20V, V_{GS} = 10V$ | - | 11 | - | | |
| Rise time | t _r *4 | I _D = 30A | - | 11 | - | | |
| Turn - off delay time | t _{d(off)} *4 | $R_L \simeq 0.67\Omega$ | - | 80 | - | ns | |
| Fall time | t _f *4 | $R_G = 10\Omega$ | - | 20 | - | | |

• Gate charge characteristics $(T_a = 25^{\circ}C)$

| Darameter | Cymah al | Conditions | | Values | | | l limit |
|----------------------|--------------------|--------------------------------|------------------------|--------|------|------|---------|
| Parameter | Symbol | | | Min. | Тур. | Max. | Unit |
| Total gate charge | O *4 | | V _{GS} = 10V | - | 46.5 | - | |
| Total gate charge | Q_g | Q_g^{*4} $V_{DD} \simeq 20V$ | | - | 23.5 | - | »C |
| Gate - Source charge | Q _{gs} *4 | I _D = 50A | V _{GS} = 4.5V | - | 8.8 | - | nC |
| Gate - Drain charge | Q _{gd} *4 | | | - | 6.7 | - | |

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Darameter | Cumbal | Conditions | Values | | | Unit | |
|----------------------------|--------------------|---|--------|------|------|------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | OHIL | |
| Continuous forward current | I _S | T = 25°C | 1 | - | 33 | Α | |
| Pulse forward current | I _{SP} *2 | T _a = 25°C | - | - | 120 | Α | |
| Forward voltage | V _{SD} *4 | $V_{GS} = 0V, I_S = 33A$ | - | - | 1.2 | V | |
| Reverse recovery time | t _{rr} *4 | I _S = 30A, V _{GS} =0V | - | 38 | - | ns | |
| Reverse recovery charge | Q _{rr} *4 | di/dt = 100A/μs | - | 24 | - | nC | |

Fig.1 Power Dissipation Derating Curve

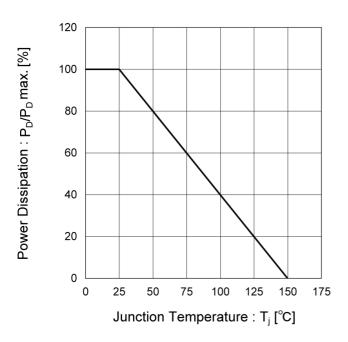
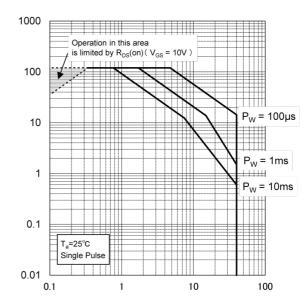


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

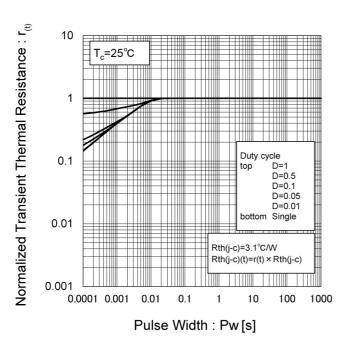


Fig.4 Single Pulse Maximum Power Dissipation

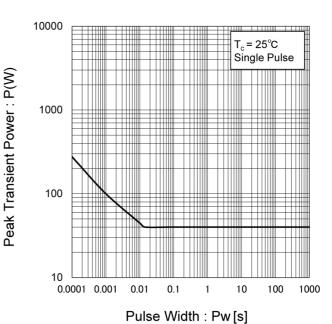


Fig.5 Typical Output Characteristics(I)

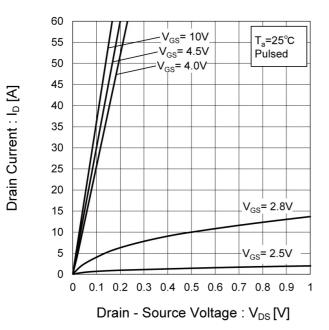
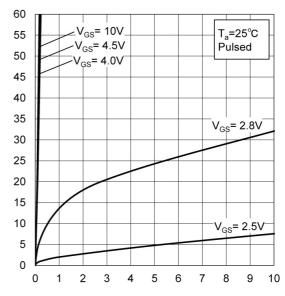


Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

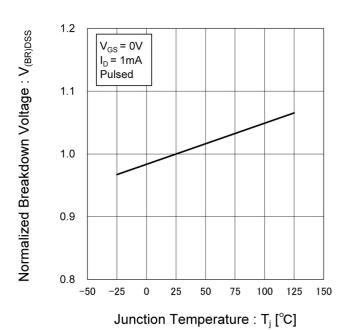


Fig.8 Typical Transfer Characteristics

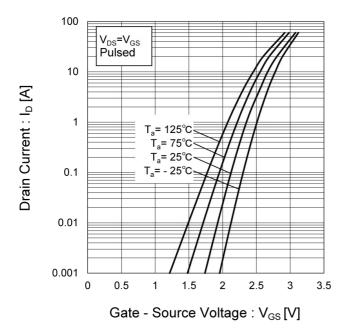


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

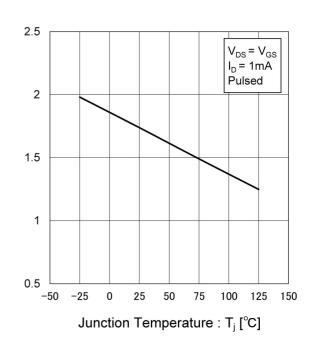
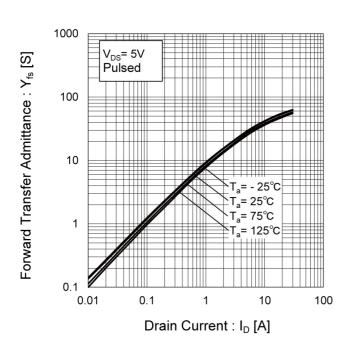


Fig.10 Forward Transfer Admittance vs.
Drain Current



Gate Threshold Voltage : $V_{GS(th)}\left[V\right]$

Fig.11 Drain Current Derating Curve

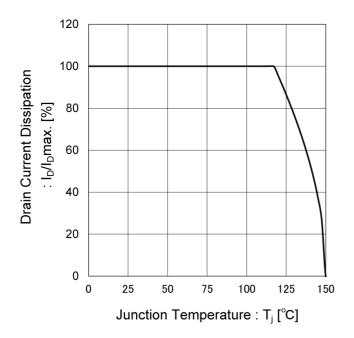
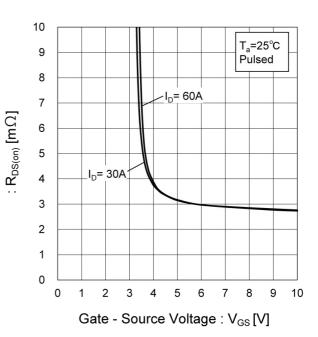


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Static Drain - Source On-State Resistance

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

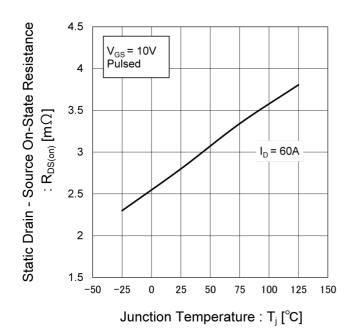


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

Static Drain - Source Ou-State Resistance Ou-State Pulsed $I_{a}=25^{\circ}\text{C}$ Pulsed $I_{a}=25^{\circ}\text{$

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

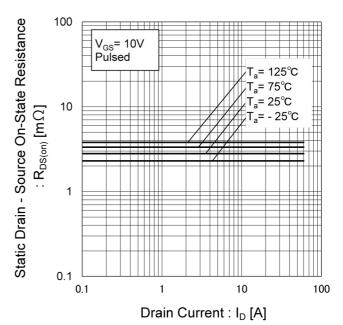


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

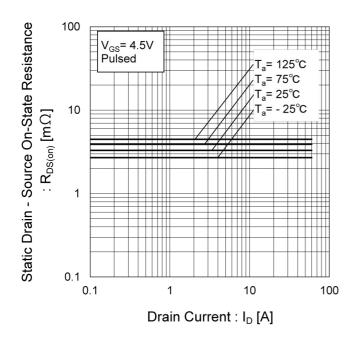


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

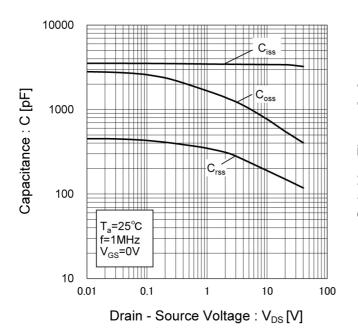


Fig.18 Switching Characteristics

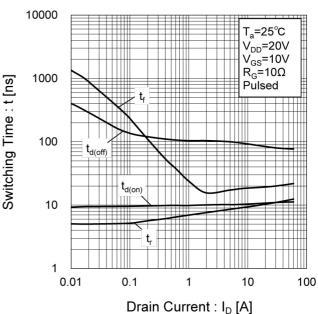


Fig.19 Typical Gate Charge

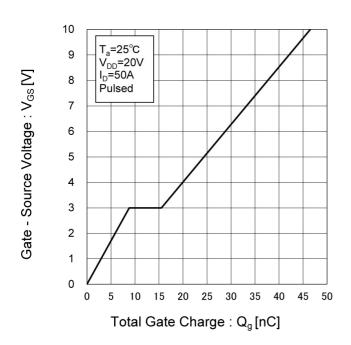
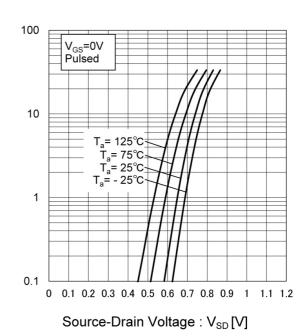


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

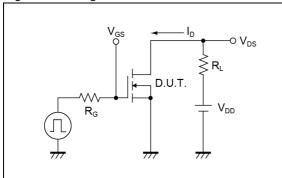


Fig.2-1 Gate Charge Measurement Circuit

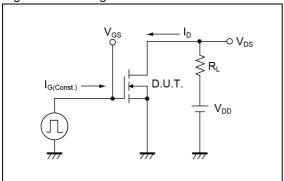


Fig.3-1 Avalanche Measurement Circuit

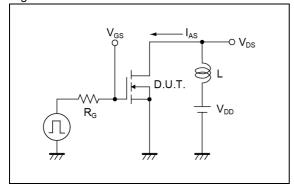


Fig.1-2 Switching Waveforms

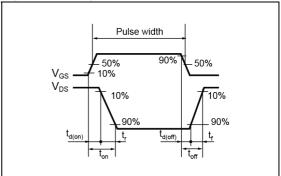


Fig.2-2 Gate Charge Waveform

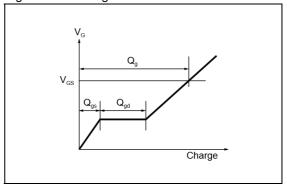
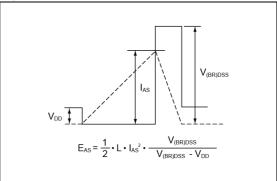
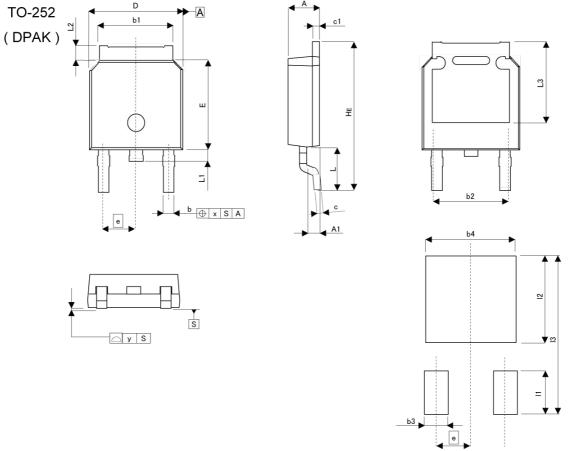


Fig.3-2 Avalanche Waveform





Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

| DIM | MILIME | ETERS | INCI | HES |
|-------|--------|-------|-------|-------|
| DIIVI | MIN | MAX | MIN | MAX |
| Α | 2.10 | 2.30 | 0.083 | 0.091 |
| A1 | 0.70 | 1.10 | 0.028 | 0.043 |
| b | 0.65 | 0.85 | 0.026 | 0.033 |
| b1 | 5.10 | 5.40 | 0.201 | 0.213 |
| b2 | 5. | 10 | 0.2 | 201 |
| С | 0.40 | 0.60 | 0.016 | 0.024 |
| c1 | 0.40 | 0.60 | 0.016 | 0.024 |
| D | 6.40 | 6.80 | 0.252 | 0.268 |
| е | 2. | 30 | 0.0 | 91 |
| Е | 6.00 | 6.40 | 0.236 | 0.252 |
| HE | 9.50 | 10.50 | 0.374 | 0.413 |
| L | 2. | 90 | 0.1 | 14 |
| L1 | 0.70 | 0.90 | 0.028 | 0.035 |
| L2 | 0.70 | 1.30 | 0.028 | 0.051 |
| L3 | 5. | 30 | 0.2 | 209 |
| Х | - | 0.25 | - | 0.010 |
| у | - | 0.10 | - | 0.004 |

| DIM | MILIME | MILIMETERS | | INCHES | | |
|-------|--------|------------|-----|--------|--|--|
| DIIVI | MIN | MAX | MIN | MAX | | |
| b3 | - | 1.10 | - | 0.043 | | |
| b4 | 1- | 5.40 | - | 0.213 | | |
| l1 | - | 2.90 | - | 0.114 | | |
| 12 | - | 5.50 | - | 0.217 | | |
| 13 | - | 10.50 | - | 0.413 | | |

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Dimension in mm/inches



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|---------|----------|------------|-----------|
| CLASSⅢ | CLASSIII | CLASS II b | CL ACCIII |
| CLASSIV | | CLASSⅢ | CLASSⅢ |

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 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
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- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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